



Material Content Data Sheet



Sales Product Name		BSC093N15NS5		Issued		24. January 2018		
MA#		MA001713378						
Package		PG-TDSON-8-7		Weight*		119.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.818	1.52	1.52	15163	15163
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		315	
	non noble metal	copper	7440-50-8	37.762	31.48	31.52	314872	315282
	noble metal	gold	7440-57-5	0.045	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		709	
	plastics	epoxy resin	-	6.033	5.03		50309	
	inorganic material	silicondioxide	60676-86-0	36.370	30.33	35.43	303270	354288
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12104	12104
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1380	1380
solder	non noble metal	tin	7440-31-5	0.050	0.04		416	
	noble metal	silver	7440-22-4	0.062	0.05		519	
	non noble metal	lead	7439-92-1	2.380	1.98	2.07	19843	20778
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.44	9.45	94391	94514
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		186	
	non noble metal	copper	7440-50-8	22.292	18.59	18.62	185876	186118
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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